

**CLAIMS**

1. A miniaturised surface mount optoelectronic component, said optoelectronic component comprising:  
5 an electrically conductive material (1), the said material is used as a base material for an assembly;  
at least an optoelectronic chip (3), the said optoelectronic chip (3) is mounted on the base; and  
an electrical connection between the optoelectronic chip (3) and the electrically  
10 conductive material (1) by a wiring means (6);  
wherein the said base material is encapsulated with a hard transparent or translucent resin material (4) to enable optical radiation to be transmitted or received via the optoelectronic component.
- 15 2. The optoelectronic component as claimed in claim 1, wherein the electrically conductive material is preferably a metal frame.
3. The optoelectronic component as claimed in claim 1, wherein a cavity (2) is provided within the electrically conductive base material.
- 20 4. The optoelectronic component as claimed in claim 1, wherein a cavity (2) is provided within the cavity.

5. The optoelectronic component as claimed in claim 1, wherein a lens structure (5) is provided to be a part of the encapsulation material.

6. The optoelectronic component as claimed in claim 1, wherein a multiple lens  
5 structure is provided to be a part of the encapsulation material.

7. The optoelectronic component as claimed in claim 1, wherein the base material (1) is crafted with a series of 'grooves' and 'wings' to enhance anchorage and minimise the occurrence of de-lamination (7).

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8. The optoelectronic component as claimed in claim 1, wherein the soldering terminals are right at the bottom of the package.

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9. The optoelectronic component as claimed in claim 1, wherein the soldering terminals are flat and have the same horizontal datum as the encapsulation material.